

### ■ Features

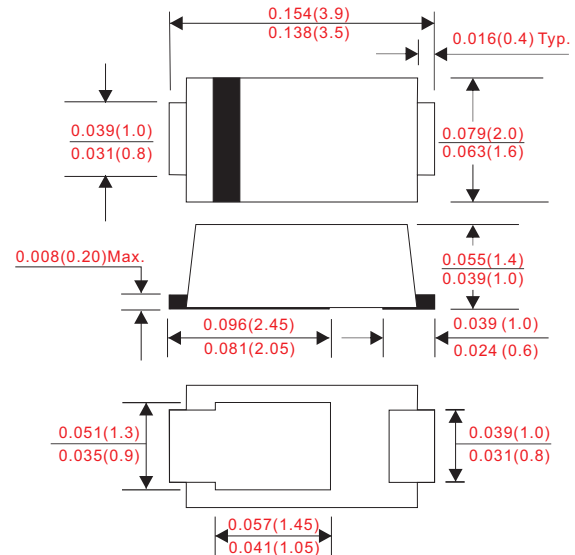
- Low profile surface mounted application in order to optimize board space.
- High current capability.
- Fast switching for high efficiency.
- High surge current capability.
- Glass passivated chip junction.
- Suffix "G" indicates Halogen free parts, ex. BFGP4001WG-ST.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

### ■ Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123ST
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Weight : Approximated 0.0155 gram

### ■ Outline

SOD-123ST



Dimensions in inches and (millimeters)

### ■ Maximum ratings and electrical characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current		$I_O$			1.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC method)	$I_{FSM}$			30	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	$I_R$			5.0	uA
	$V_R = V_{RRM} \quad T_A = 125^\circ\text{C}$				100	
Thermal resistance	Junction to ambient	$R_{\theta JA}$		42		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$		15		pF
Storage temperature		$T_{STG}$	-55		+150	°C

Symbol	Marking code	Max. repetitive peak reverse voltage $V_{RRM}$ (V)	Max. RMS voltage $V_{RMS}$ (V)	Max. DC blocking voltage $V_R$ (V)	Max. forward voltage @1A, $T_A = 25^\circ\text{C}$ $V_F$ (V)	Max. reverse recovery time(1) $T_{rr}$ (ns)	Operating temperature $T_J$ (°C)
BFGP4001W-ST	F1	50	35	50	1.30	150	-55 ~ +150
BFGP4002W-ST	F2	100	70	100			
BFGP4003W-ST	F3	200	140	200			
BFGP4004W-ST	F4	400	280	400		250	
BFGP4005W-ST	F5	600	420	600			
BFGP4006W-ST	F6	800	560	800		500	
BFGP4007W-ST	F7	1000	700	1000			

Note : 1.  $I_F = 0.5A$ ,  $I_R = 1.0A$ ,  $I_{RR} = 0.25A$

### Rating and characteristic curves

FIG.1-TYPICAL FORWARD CHARACTERISTICS

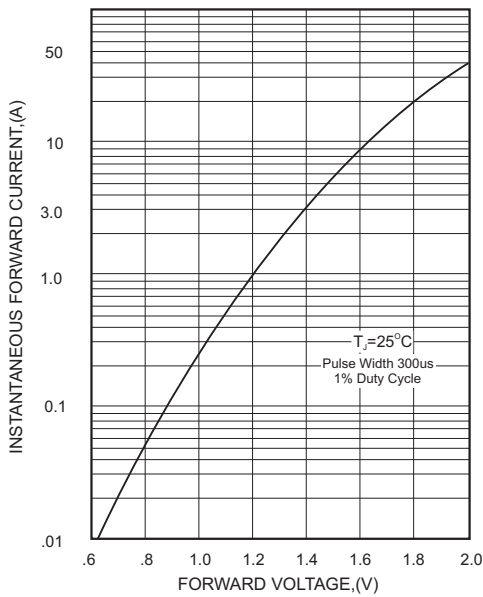


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

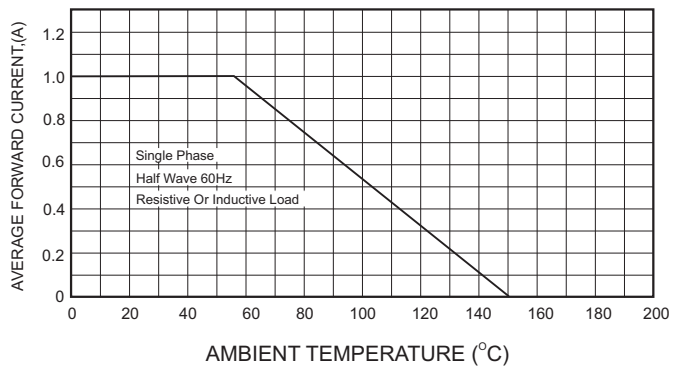
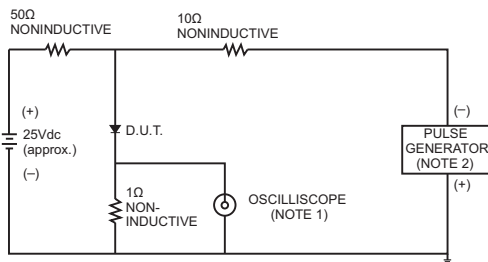


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.  
2. Rise Time= 10ns max., Source Impedance= 50 ohms.

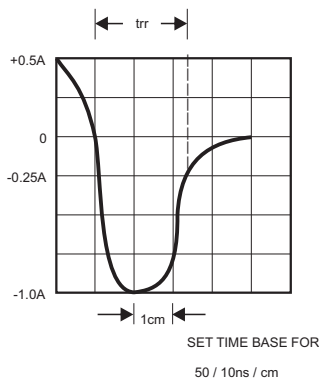


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

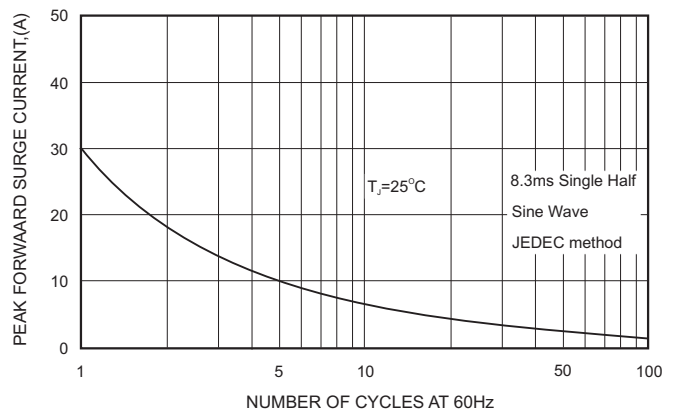
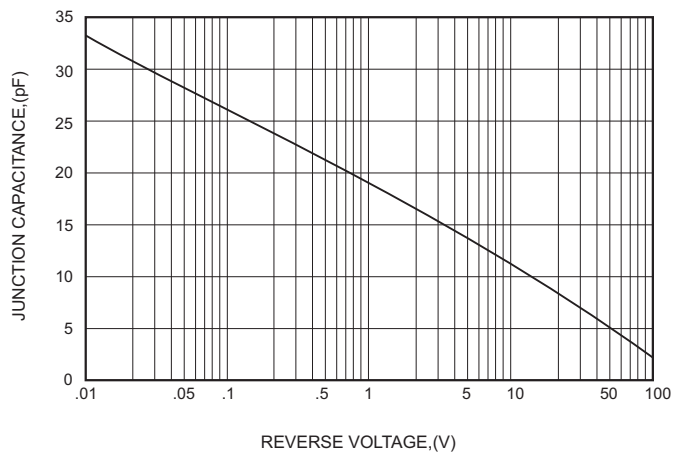
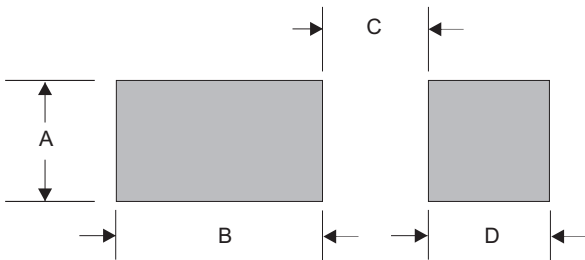


FIG.5-TYPICAL JUNCTION CAPACITANCE



■ SOD-123ST foot print



A	B	C	D
0.036 (0.90)	0.084 (2.10)	0.032 (0.80)	0.032 (0.80)

Dimensions in inches and (millimeters)

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